

Part Number: PSA12-11SEKWA

Super Bright Orange

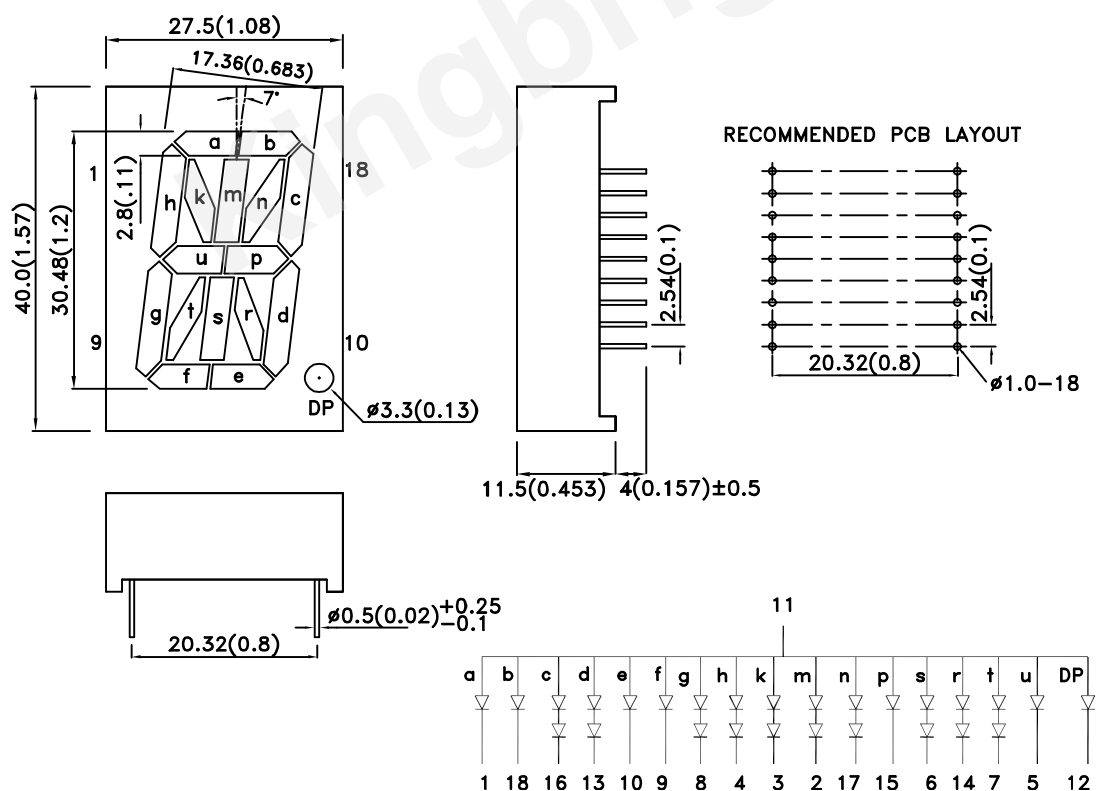
Features

- 1.2 inch character height .
- Low current operation.
- High contrast and light output.
- Easy mounting on P.C. boards or sockets.
- Categorized for luminous intensity.
- Mechanically rugged.
- Standard:gray face, white segment.
- RoHS compliant.

Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions& Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
PSA12-11SEKWA	Super Bright Orange (InGaAlP)	White Diffused	52000	110000	Common Anode, Rt. Hand Decimal.
			*21000	*37000	

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter		Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength		Super Bright Orange	610		nm	I _F =20mA
λ_D [1]	Dominant Wavelength		Super Bright Orange	601		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width		Super Bright Orange	29		nm	I _F =20mA
C	Capacitance		Super Bright Orange	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	c,d,g,h,k,m,n,s,r,t	Super Bright Orange	4.2	5.0	V	I _F =20mA
		a,b,e,f,p,u and DP		2.1	2.5		
I _R	Reverse Current (Per Chip)	c,d,g,h,k,m,n,s,r,t	Super Bright Orange		10	uA	V _R =5V
		a,b,e,f,p,u and DP			10		

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

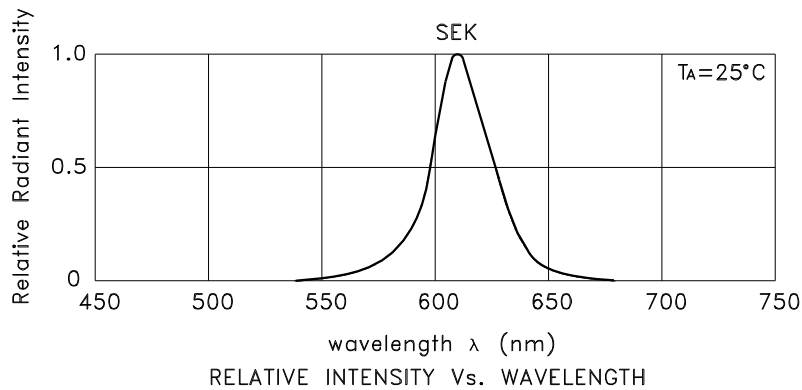
Absolute Maximum Ratings at TA=25°C

Parameter		Super Bright Orange	Units
Power dissipation	c,d,g,h,k,m,n,s,r,t	150	mW
	a,b,e,f,p,u and DP	(75)	
DC Forward Current	c,d,g,h,k,m,n,s,r,t	30	mA
	a,b,e,f,p,u and DP	(30)	
Peak Forward Current [1]	c,d,g,h,k,m,n,s,r,t	195	mA
	a,b,e,f,p,u and DP	(195)	
Reverse Voltage (Per Chip)	c,d,g,h,k,m,n,s,r,t	5	V
	a,b,e,f,p,u and DP		
Operating / Storage Temperature		-40°C To +85°C	
Lead Solder Temperature[2]		260°C For 3-5 Seconds	

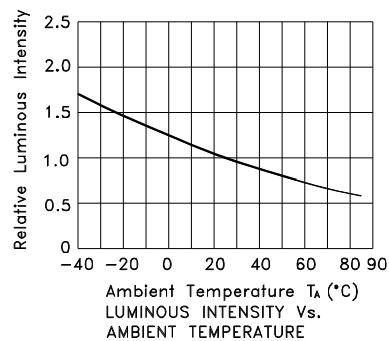
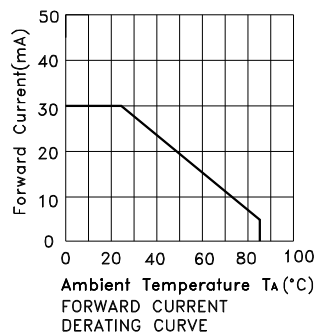
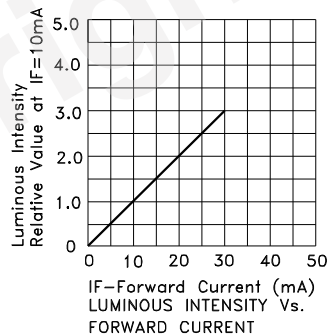
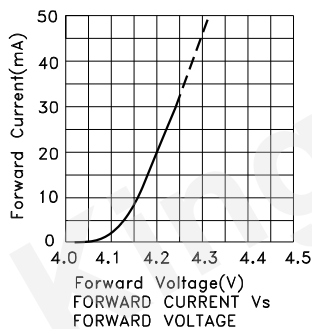
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

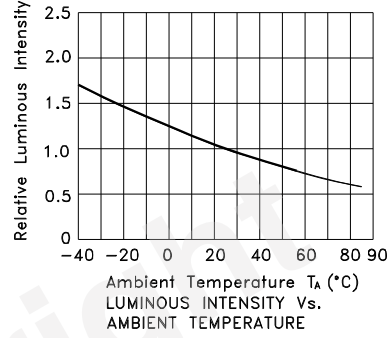
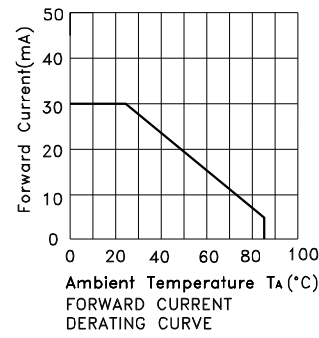
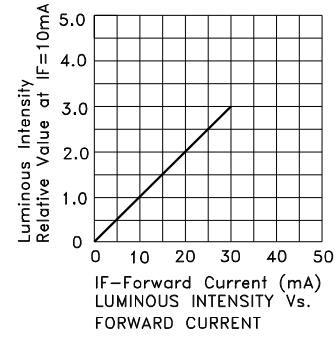
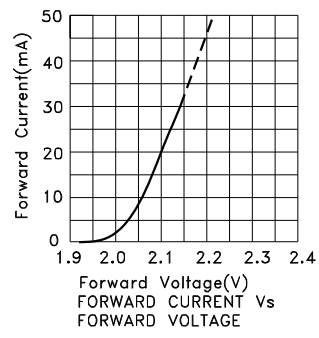
2. 2mm below package base.



Super Bright Orange PSA12-11SEKWA



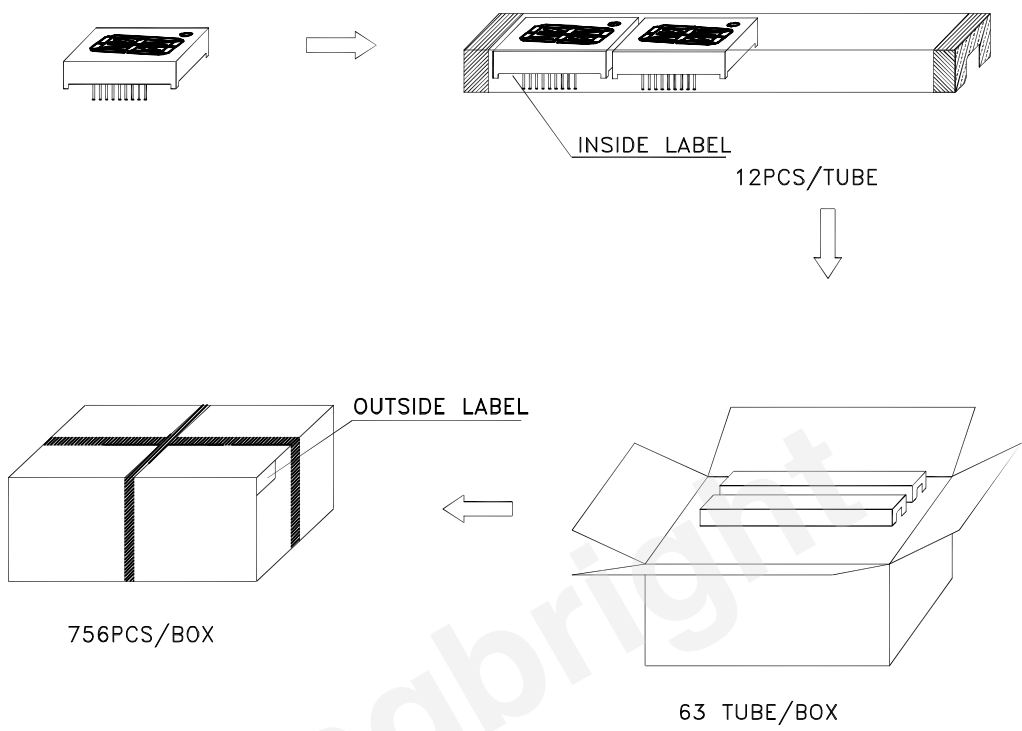
Note:the curves are on the segment c,d,g,h,k,m,n,s,r and t.




Note:the curves are on the segment a,b,e,f,p,u and DP.

PACKING & LABEL SPECIFICATIONS

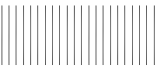
PSA12-11SEKWA



Inside Label On IC-tube

Kingbright	TYPE: PSx12-11xxx	PASSED xx xx xx FQCx	Date
	QTY: 12 PCS CODE: xx		
			
XXXXXXXXXX-XXXX		Number OF FQC	
LOT NO.		RoHS Compliant	

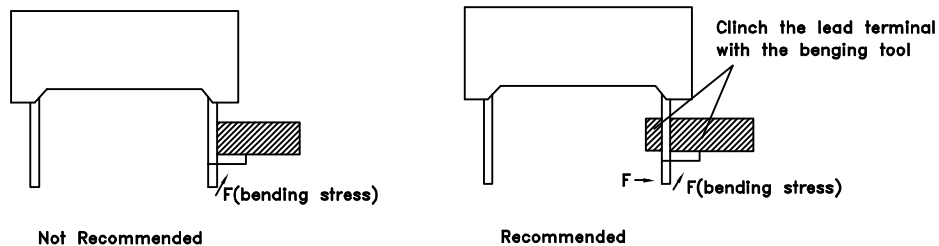
Outside Label On Box

XXXXXX		
PSx12-11xxx	Bin Code	Number OF QA
756 PCS	XX	Date
	QAx xx xx xx PASSED	
	RoHS Compliant	

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

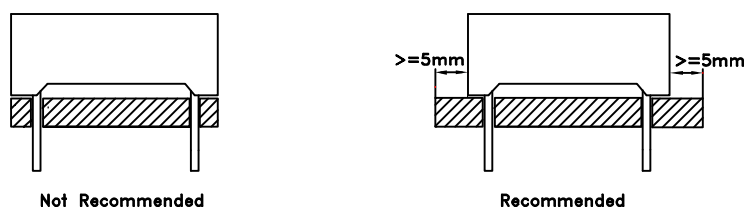


Installation

- 1.The installation process should not apply stress to the lead terminals.
- 2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

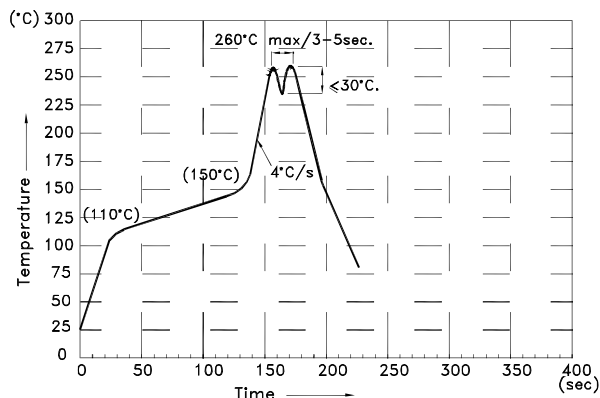


- 3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C
5. No more than once.

Soldering General Notes:

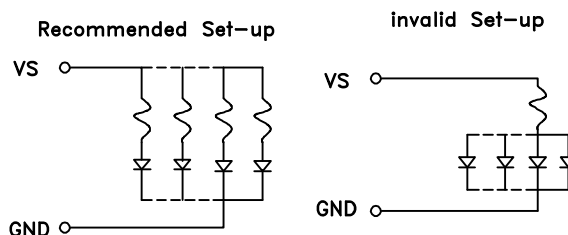
1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.



Detailed application notes are listed on our website.

http://www.kingbright.com/application_notes